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1. Device (1) for sorting wafers which are stored in cassettes, comprising a part for receiving at least two cassettes (18, 19) and a wafer-handling device (24), the part for receiving said cassettes being arranged in a housing (2), in which a store (8) for cassettes and a cassette/handling device (25) are arranged, characterised in that, said wafer/handling device is provided for moving the wafers into and out of the cassette from and to the other cassette, and in that such store for cassette and said cassette/handling device are separated from said part for receiving cassettes.
2. Sorting device according to Claim 1, in which the said wafer-handling device (24) is arranged in a chamber (22) which can be sealed off with respect to the said housing (2).
3. Sorting device according to one of the preceding claims, in which said chamber (22) comprises a measuring station (16) functionally connected with said wafer handling device.
4. Sorting device according to one of the preceding claims, in which the part for receiving at least two cassettes comprises a turntable (30).
5. Sorting device according to one of the preceding claims, in which the said store (8) for cassettes comprises a rotatable magazine.
6. Method for assembling a batch of wafers in cassettes comprising placing at least two cassettes in active connection with a wafer handling device, said wafer handling device being used to carry out a sorting operation by transferring wafers from one cassette to the other, wherein said cassettes are from a store, and move from said store to said sorting operation by cassette handling device wherein a first cassette in the store is selected, and moved from the store to the sorting operation by said cassette handling device and a second cassette in the store is selected, and moved from the store to the sorting operation by said cassette handling device, characterised in that said first and second cassettes are moved independently from each other to said sorting operation from said store.

7. Method according to Claim 6, comprising testing said wafers during the sorting operation.

ADD A4

Add B5

[illegible]